PMP11065_RevC_BOM.xlsx

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PMP11065 REV C Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C25, C28	2	100pF	GRM1885C1H101JA01D	MuRata	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	603
C9, C21	2	470pF	C1608C0G1H471J	TDK	CAP, CERM, 470pF, 50V, +/-5%, C0G/NP0, 0603	603
C15, C26	2	4700pF	GRM188R71H472KA01D	MuRata	CAP, CERM, 4700 pF, 50 V, +/- 10%, X7R, 0603	603
C17, C18	2	0.01uF	C1608X7R1H103K	TDK	CAP, CERM, 0.01 µF, 50 V, +/- 10%, X7R, 0603	603
C29	1	0.068uF	GRM188R71E683KA01D	MuRata	CAP, CERM, 0.068 µF, 25 V, +/- 10%, X7R, 0603	603
C19	1	0.15uF	C1608X7R1E154K080AA	TDK	CAP, CERM, 0.15 µF, 25 V, +/- 10%, X7R, 0603	603
C20	1	100pF	GRM21A5C2E101JW01D	MuRata	CAP, CERM, 100 pF, 250 V, +/- 5%, C0G/NP0, 0805	805
C1, C8, C10	3	0.1uF	C2012X7R2A104K	TDK	CAP, CERM, 0.1uF, 100V, +/-10%	805
C11, C30	2	1uF	C2012X5R1E105K	TDK	CAP, CERM, 1uF, 25V, +/-10%, X5R, 0805	805
C4, C5, C6, C7	4	2.2uF	GRM32ER72A225KA35L	MuRata	CAP, CERM, 2.2uF, 100V, +/-10%, X7R, 1210	1210
C12, C13, C14, C22, C23, C24	6	100uF	GRM32ER60J107ME20L	MuRata	CAP, CERM, 100uF, 6.3V, +/-20%, X5R, 1210	1210
C2, C27	2	2200pF	C4532X7R3D222K	TDK	CAP, CERM, 2200 pF, 2000 V, +/- 10%, X7R, 1812	1812
C16	1	22uF	EEE-FK1E220R	Panasonic	CAP, AL, 22uF, 25V, +/-20%, 0.7 ohm, SMD	SMT Radial C
C3	1	22uF	EEE-FK2A220P	Panasonic	CAP, AL, 22uF, 100V, +/-20%, 1.3 ohm, SMD	SMT Radial F
D1	1		B160-13-F	Diodes Inc.	Diode, Schottky, 60 V, 1 A, SMA	SMA
D2, D3, D5, D6, D7, D8	6		MMSD4148T1G	ON Semiconductor	Diode, Switching, 100V, 0.2A, SOD-123	SOD-123
D4	1		ES2D-13-F	Diodes Inc.	Diode, Ultrafast, 200V, 2A, SMB	SMB
D9	1		BAT54S-7-F	Diodes Inc.	Diode, Schottky, 30V, 0.2A, SOT-23	SOT-23
J1, J2, J3	3		ED555/2DS	OST	Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm
L1	1	3.3uH	LPS4018-332MLB	Coilcraft	Inductor, Shielded Drum Core, Ferrite, 3.3uH, 1.9A, 0.08 ohm, SMD	LPS4018
Q1, Q3	2		CSD17577Q3A	Texas Instruments	MOSFET, N-CH, 30 V, 19 A, SON 3.3x3.3mm	SON 3.3x3.3mm
Q2, Q5	2		MMBT3906	Fairchild Semiconductor	Transistor, PNP, 40V, 0.2A, SOT-23	SOT-23
Q4	1		BSC520N15NS3 G	Infineon Technologies	MOSFET, N-CH, 150 V, 21 A, PG-TDSON-8	PG-TDSON-8
R21	1	0	ERJ-3GEY0R00V	Panasonic	RES, 0 ohm, 5%, 0.1W, 0603	603
R2, R10	2	4.7	CRCW06034R70JNEA	Vishay-Dale	RES, 4.7 ohm, 5%, 0.1W, 0603	603
R5, R13	2	10	CRCW060310R0JNEA	Vishay-Dale	RES, 10, 5%, 0.1 W, 0603	603
R22	1	237	CRCW0603237RFKEA	Vishay-Dale	RES, 237 ohm, 1%, 0.1W, 0603	603
R17	1	332	CRCW0603332RFKEA	Vishay-Dale	RES, 332 ohm, 1%, 0.1W, 0603	603
R14	1	340	CRCW0603340RFKEA	Vishay-Dale	RES, 340, 1%, 0.1 W, 0603	603
R25	1	1.00k	CRCW06031K00FKEA	Vishay-Dale	RES, 1.00k ohm, 1%, 0.1W, 0603	603
R11	1	3.83k	CRCW06033K83FKEA	Vishay-Dale	RES, 3.83 k, 1%, 0.1 W, 0603	603
R4, R16	2	4.99k	CRCW06034K99FKEA	Vishay-Dale	RES, 4.99k ohm, 1%, 0.1W, 0603	603
R26	1	5.90k	CRCW06035K90FKEA	Vishay-Dale	RES, 5.90k ohm, 1%, 0.1W, 0603	603
R23, R24	2	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0k ohm, 1%, 0.1W, 0603	603
R12	1	25.5k	CRCW060325K5FKEA	Vishay-Dale	RES, 25.5 k, 1%, 0.1 W, 0603	603
R7	1	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.1 W, 0603	603
R8, R9, R18, R20	4	6.8	CRCW08056R80JNEA	Vishay-Dale	RES, 6.8 ohm, 5%, 0.125W, 0805	805
R6	1	20	CRCW080520R0JNEA	Vishay-Dale	RES, 20 ohm, 5%, 0.125W, 0805	805
R19	1	0.15	CSRN2010FKR150	Stackpole Electronics Inc	RES, 0.15, 1%, 1 W, 2010	2010
R1	1	1.0k	CRCW20101K00JNEF	Vishay-Dale	RES, 1.0 k, 5%, 0.75 W, 2010	2010
R15	1	75	CRCW251275R0JNEG	Vishay-Dale	RES, 75, 5%, 1 W, 2512	2512
R3	1	30k	CRCW251230K0JNEG	Vishay-Dale	RES, 30 k, 5%, 1 W, 2512	2512
T1	1		LDT0656-50	Linkcom Manufacturing Co.	Transformer, 75 uH, SMT	SMD, 12-Leads, Body 22x18mm, Pitch 3mm
U2	1		HMHA2801A	Fairchild Semiconductor	Optocoupler, 3.75kV RMS, SMT	Mini Flat Package
U1	1		LM5020MM-1/NOPB	Texas Instruments	100V Current Mode PWM Controller, 10-pin MSOP, Pb-Free	MUB10A
U3	1		TLV431AIDBV	Texas Instruments	LOW-VOLTAGE ADJUSTABLE PRECISION SHUNT REGULATOR, DBV0005A	DBV0005A

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